

Thermal RC network (Foster)

SPICE thermal model

ymbol	Parameter	Conditions	Min	Тур	Max	Unit
th(j-mb)	thermal resistance from junction to mounting base		-	-	0.51	K/W
	Cth ₁	5.937E-05 F		Ą	t .	
	Cth ₂	2.470E-03 F		_	t <u>j</u>	
	Cth ₃	1.156E-03 F			<u></u>	
	Cth ₄	5.632E-03 F			Rth1 Cth1	
	Cth ₅	1.391E-02 F		l l		
	Cth ₆	3.008E-02 F				
	Cth ₇	5.660E-01 F		г	$\begin{bmatrix} \bullet & \bullet \\ \bullet & \bullet \end{bmatrix}$	
	Cth ₈	1.244E+02 F			$\int Rth_2 + Cth_2$	
	Rth₁	7.141E-04 Ω				
	Rth ₂	5.029E-04 Ω		Г	5	
	Rth ₃	8.856E-03 Ω			Rth3 🛨 Cth3	
	Rth ₄	1.911E-02 Ω		L	╧╺	
	Rth₅	8.135E-02 Ω				
	Rth ₆	2.751E-01 Ω			Rth4 📥 Cth4	
	Rth ₇	1.231E-01 Ω				
	Rth ₈	1.303E-03 Ω	((P)		
				\checkmark ,	$\neg \neg \neg$	
					Rth5 📥 Cth5	
				L	╧╼╴╴	
					_	
					Rth6 Cth6	
				Г	$\neg \bullet \neg $	
					Rth7 🚔 Cth7	
				L	╧┓	
art:	PSMN7R8-100PSE			[
ete:	0/40/2044				$\operatorname{Rth}_8 = \operatorname{Cth}_8$	
ate:	9/10/2014					
	0.51 K/W			└── †	tomb	
				\diamond	amb 001aal768	2
lodel Rth	0.51 K/W			↓ ↓	 t _{amb} 	aal768

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